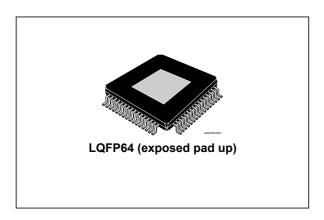


2x150 W/1x300 W class D digital input automotive power amplifier with diagnostics features and low voltage

Data brief



Features



- · AEC-Q100 (rev. G) qualified
- Integrated 110 dB D/A conversion
- I²S and TDM digital input (3.3/1.8 V)
- Input sampling frequency: 44.1 kHz, 48 kHz, 96 kHz, 192 kHz
- Full I²C bus driving (3.3/1.8 V) with 8 different I²C bus addresses
- EMI control for FM/AM compatibility
- EMI compliance evaluated following normative IEC61967-4 and IEC62132-4
- Low radiation function (LRF)
- Very low quiescent current
- Output low-pass filter included in the feedback allowing outstanding audio performances
- Wide operating supply range: target 5.5 V-50 V

- MOSFET power outputs allowing high output power capability under step-up voltage:
 - 2 x 120 W /4 Ω @ 35 V, 1 kHz THD = 1% (2 x150 W /4 Ω @ 35 V, 1 kHz THD =10%)
 - 2 x 140 W /8 Ω @ 50 V, 1 kHz THD = 1%
 (2 x180 W /8 Ω @ 50 V, 1 kHz THD =10%)
 - 2 x 270 W /8 Ω @ 50 V max output power
- Operation under standard car battery with high output power:
 - 2 x 22 W /4 Ω @ 14 V, 1 kHz THD = 1% (2 x 28 W /4 Ω @ 14 V, 1 kHz THD = 10%)
 - 2 x 37 W /2 Ω @ 14 V, 1 kHz THD = 1% (2 x 46 W /2 Ω @ 14 V, 1 kHz THD = 10%)
- Possibility to drive 2 Ω loads (until 18 V)
- Independent channel operation
- I²C bus diagnostics:
 - Short to Vcc/GND diagnostic (including soft shorts up to 1k Ω)
 - DC load diagnostic
 - AC load diagnostic (working both with internally generated and externally generated tone)
- Integrated fault protection
- · Input and output offset detector
- Clipping detector
- Legacy mode ('no I²C' mode)
- Short circuit and ESD integrated protections
- Package: LQFP64 exposed pad up

Table 1. Device summary

Order code	Package	Packing
FDA802-VYY	LQFP64 (exp. pad up)	Tray
FDA802-VYT	LQFP64 (exp. pad up)	Tape & reel

Contents FDA802

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FDA802 Description

1 Description

The FDA802 is a dual bridge class D amplifier, designed in the most advanced BCD technology specially intended for car radio applications.

The FDA802 integrates a high performance D/A converter together with powerful MOSFET outputs in class D, to get an outstanding efficiency compared to the standard class AB.

The integrated D/A converter allows to reach outstanding performances (110 dB S/N ratio with 110 dB of dynamic range).

Thanks to the high-voltage MOSFET output stages it can operate both under standard car battery (6-18 V) and under boosted power supply (up to 50 V) to reach the highest possible power with integrated solution.

The feedback loop is including the output L-C low-pass filter, allowing superior frequency response linearity and lower distortion independently from the inductor and capacitor quality.

FDA802 is fully configurable through I²C bus interface and integrates a complete diagnostics array specially intended for automotive applications.

Thanks to the solutions implemented to solve the EMI problems, the device is intended to be used in the standard single DIN car-radio box together with the tuner.

Moreover FDA802 is able to work with power supply as low as 5.5 V, thus supporting the most recent low voltage ('start-stop') car-makers specification.

2 Block and pins description diagrams

GAPG1905150709PS Feedback2-Out1+ Out1-Out2+ Out2-PWM Transresistance Power Amplifier PWM Transresistance Power Amplifier Dgnd DGSVR D1V8SVR DVdd Current Generators Array Current Generators Array GND2 SVR 62 Agnd VCC2 AGSVR A5VSVR 61 AVdd Vbattery Scrambler ch1 Scrambler ch2 GND1 4/5 VCC1 14/ 15 Vbattery I2Cclk Interpolator & & Noise Shaper CD/Diag 12C 49 Enable3 TAB 21 Enable2 63 HWMute 22 Enable1 I2S interface Charge Pump CPump1 PL CPump2 12Sws 12Sdata1 12Sdata2

Figure 1. Block diagram



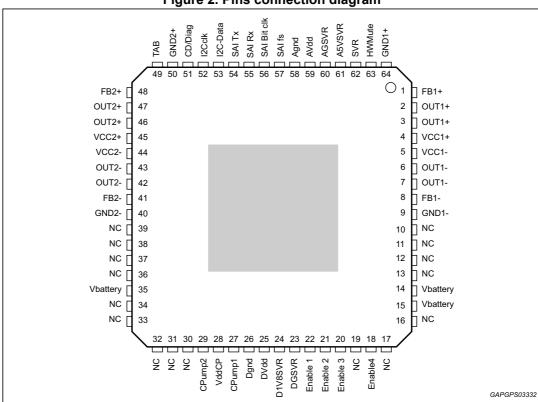


Figure 2. Pins connection diagram

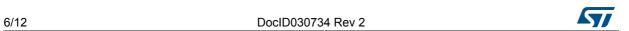
Table 2. Pins list description

N#	Pin	Function	
1	FB1+	Channel 1, half bridge plus, Feedback	
2	OUT1+	Channel 1, half bridge plus, Output	
3	OUT1+	Channel 1, half bridge plus, Output	
4	VCC1+	Channel 1, half bridge plus, Boosted Power Supply	
5	VCC1-	Channel 1, half bridge minus, Boosted Power Supply	
6	OUT1-	Channel 1, half bridge minus, Output	
7	OUT1-	Channel 1, half bridge minus, Output	
8	FB1-	Channel 1, half bridge minus, Feedback	
9	GND1-	Channel 1, half bridge minus, Power Ground	
10-13, 16-17, 19, 30-34, 36-39	N.C.	Not connected	
14	Vbattery	Main battery voltage (14V)	
15	Vbattery	Main battery voltage (14V)	
18	Enable4	Chip Enable 4	
20	Enable3	Chip Enable 3	



Table 2. Pins list description (continued)

N#	Pin	Function	
21	Enable2	Chip Enable 2	
22	Enable1	Chip Enable 1	
23	DGSVR	Negative Analog Supply V(SVR)-0.9V (Internally generated)	
24	D1V8SVR	Positive Digital Supply V(SVR)+0.9V (Internally generated)	
25	DVdd	Digital supply	
26	Dgnd	Digital ground	
27	CPump1	Charge Pump pin1	
28	VddCP	Charge Pump output voltage	
29	CPump2	Charge Pump pin2	
35	Vbattery	Main battery voltage (14V)	
40	GND2-	Channel 2, half bridge minus, Power Ground	
41	FB2-	Channel 2, half bridge minus, Feedback	
42	OUT2-	Channel 2, half bridge minus, Output	
43	OUT2-	Channel 2, half bridge minus, Output	
44	VCC2-	Channel 2, half bridge minus, Boosted Power Supply	
45	VCC2+	Channel 2, half bridge plus, Boosted Power Supply	
46	OUT2+	Channel 2, half bridge plus, Output	
47	OUT2+	Channel 2, half bridge plus, Output	
48	FB2+	Channel 2, half bridge plus, Feedback	
49	TAB	Device slug connection	
50	GND2+	Channel 2, half bridge plus, Power Ground	
51	CD/Diag	Clip detector / diagnostic pin	
52	I2CClk	I ² C clock	
53	I2C-Data	I ² C Data Input	
54	SAI Tx	I ² S/TDM Data 2 (Data output)	
55	SAI Rx	I ² S/TDM Data 1 (Data input)	
56	SAI Bit clk	I ² S/TDM Clock	
57	SAI fs	I ² S/TDM Sws (Frame Sync Input)	
58	Agnd	Analog ground	
59	AVdd	Analog supply	
60	AGSVR	Negative Analog Supply V(SVR)-2.5V (Internally generated)	
61	A5VSVR	Positive Analog Supply V(SVR)+2.5V (Internally generated)	
62	SVR	Supply Voltage Ripple Rejection Capacitor	
63	HWMute	Hardware mute pin	
64	GND1+	Channel 1, half bridge plus, Power Ground	



FDA802 Package information

3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.

ECOPACK® is an ST trademark.

3.1 LQFP64 (10x10x1.4 mm exp. pad up) package information

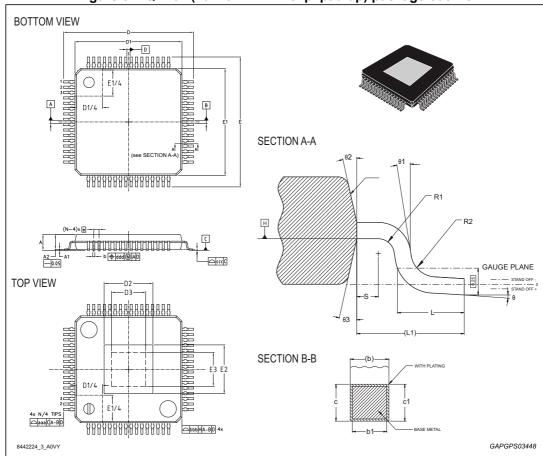


Figure 3. LQFP64 (10x10x1.4 mm exp. pad up) package outline

Package information FDA802

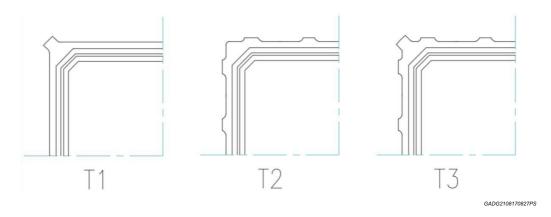
Table 3. LQFP64 (10x10x1.4 mm exp. pad up) package mechanical data

	Dimensions in mm		
Symbol	Min.	Тур.	Max.
Θ	0°	3.5°	6°
θ1	0°	9°	12°
Θ2	11°	12°	13°
θ3	11°	12°	13°
А	-	-	1.49
A1	-0.04	-	0.04
A2	1.35	1.4	1.45
b	-	-	0.27
b1	0.17	0.20	0.23
С	0.09	-	0.20
c1	0.09	0.127	0.16
D	12.00 BSC		
D1 ⁽¹⁾ (2)	10.00 BSC		
D2	See VARIATIONS		
е	0.50 BSC		
E	12.00 BSC		
E1 ⁽¹⁾ (2)	10.00 BSC		
E2	See VARIATIONS		
L	0.45	0.60	0.75
L1		1.00 REF	
N	-	64	-
R1	0.08	-	-
R2	0.08	-	0.20
S	0.20	-	-
Į.	Tolerance of	form and position	1
aaa	-	0.20	-
bbb	-	0.20	-
ccc	-	0.08	-
ddd	-	0.08	-
		<u> </u>	

Table 3. LQFP64 (10x10x1.4 mm exp. pad up) package mechanical data (continued)

		171 0	,
Symbol	Dimensions in mm		
	Min.	Тур.	Max.
VARIATIONS			
Pad option 6.0x6.0 (T1-T3) ⁽³⁾			
D2	-	-	6.61
E2	-	-	6.61
D3	4.8	-	-
E3	4.8	-	-

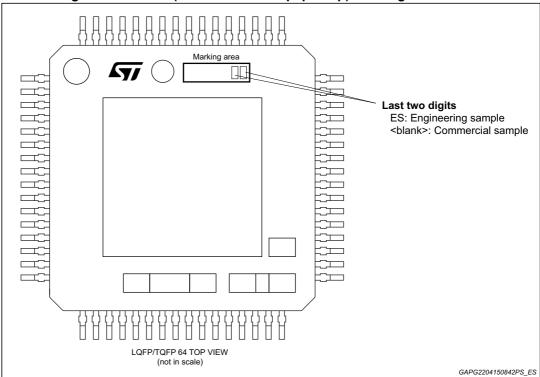
- 1. Dimensions D1 and E1 do not include mold flash or protrusions. Allowable mold flash or protrusion is "0.25 mm" per side.
- 2. The Top package body size may be smaller than the bottom package size by much as 0.15 mm.
- 3. Number, dimensions and position of shown groves are for reference only:



Package information FDA802

3.2 LQFP64 (10x10x1.4 mm exp. pad up) marking information

Figure 4. LQFP64 (10x10x1.4 mm exp. pad up) marking information



Parts marked as 'ES' are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted to run a qualification activity prior to any decision to use these engineering samples.

FDA802 Revision history

4 Revision history

Table 4. Document revision history

Date	Revision	Changes
14-Jun-2017	1	Initial release.
22-Aug-2017	2	Updated LQFP64 (10x10x1.4 mm exp. pad up) package information.

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